

In the Claims:

1     **1.**     (Original) An electronic device (1)  
2             -     with a base plate (2),  
3             -     with an electronics housing (3) which is connected to  
4             the base plate (2), with at least one bond contact  
5             bearer (5),  
6             characterised in that the bond contact bearer (5) is  
7             supported on the base plate (2) by a supporting body (6) in  
8             such a manner that the supporting body (6) exerts a  
9             pretension force onto the bond contact bearer (5).

1     **2.**     (Original) An electronic device according to claim 1,  
2             characterised in that a projection of the supporting body  
3             (6) above the base plate (2) is greater than the distance  
4             between the bond contact bearer (5) and the base plate (2).

**Claims 3 and 4 (Canceled).**

1     **5.**     (Original) A procedure for bonding an electronic device (1)  
2             with the following procedural stages:  
3             -     provision of a base plate (2),  
4             -     connection of an electronics housing (3) via a  
5             supporting body (6) with the base plate (2) in such a

6 manner that the supporting body (6) exerts a  
7 pretension force onto the bond contact bearer (5),  
8 - creation of a bond connection between the bond contact  
9 bearer (5) of the electronics housing (3) and an  
10 additional bond contact bearer.

1 6. (New) An electronic device according to claim 1,  
2 characterized in that the supporting body (6) represents a  
3 separate component from the base plate (2), which is  
4 mechanically connected to the electronics housing (3).

1 7. (New) An electronic device according to claim 1,  
2 characterized in that the supporting body (6) is designed  
3 as a projecting ring or as a plurality of projecting  
4 individual segments.

**[REMARKS FOLLOW ON NEXT PAGE]**